

Description

The HXY30N10D uses advanced trench technology to provide excellent $R_{\text{DS}(\text{ON})}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



TO252-2L

General Features

 $V_{DS} = 100V I_{D} = 30A$

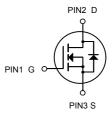
 $R_{DS(ON)}$ < 43m Ω @ V_{GS} =10V

Application

Battery protection

Load switch

Uninterruptible power supply



N-Channel MOSFET

Package Marking and Ordering Information

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Product ID	Pack	Marking	Qty(PCS)	
HXY30N10D	TO252-2L	30N10 XXX YYYY	2500	

Absolute Maximum Ratings Tc=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	100	V
Vgs	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	30	А
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	13.5	А
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	Continuous Drain Current, V _{GS} @ 10V¹ 4.2	
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹) 10V ¹ 3.4	
Ідм	Pulsed Drain Current ²	45	А
EAS	Single Pulse Avalanche Energy ³	36.5	mJ
las	Avalanche Current	27	А
P _D @T _C =25°C	Total Power Dissipation⁴	52.1	W
P _D @T _A =25°C	Total Power Dissipation ⁴	2	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
Reja	Thermal Resistance Junction-ambient ¹	62	°C/W
R _θ JC	Thermal Resistance Junction-Case ¹	2.4	°C/W



Electrical Characteristics (T_C=25 ℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100			V	
△BV _{DSS} /△T	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA		0.098		V/°C	
		V _{GS} =10V , I _D =20A		35	43		
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =15A		40	50	mΩ	
$V_{GS(th)}$	Gate Threshold Voltage		1.3		2.5	V	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	V _{GS} =V _{DS} , I _D =250uA		-5.52		mV/℃	
1	Dunin Course Leakens Current	V_{DS} =80V , V_{GS} =0V , T_{J} =25 $^{\circ}$ C			10		
IDSS	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =55℃			100	uA	
Igss	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =20A		28.7		S	
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.6	3.2	Ω	
Qg	Total Gate Charge (10V)			60	84		
Qgs	Gate-Source Charge	V _{DS} =80V , V _{GS} =10V , I _D =20A		9.7	14	nC	
Qgd	Gate-Drain Charge			11.8	16.5		
Td(on)	Turn-On Delay Time			10.4	21		
Tr	Rise Time			46	83		
Td(off)	Turn-Off Delay Time	I _D =20A		54	108	ns	
Tf	Fall Time			10	20		
Ciss	Input Capacitance			3848	5387		
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		137	192	pF	
Crss	Reverse Transfer Capacitance			82	115		
ls	Continuous Source Current ^{1,5}				22	Α	
Ism	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current			45	Α	
Vsp	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V	
trr	Reverse Recovery Time	IF=20A , dI/dt=100A/μs ,		30		nS	
Qrr	Reverse Recovery Charge	T _J =25°C		37		nC	

Note:

^{1.}The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

^{2.}The data tested by pulsed , pulse width $\,\leq\,300\text{us}$, duty cycle $\,\leq\,2\%$

^{3.} The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS} =27A

^{4.}The power dissipation is limited by 150°C junction temperature

^{5.} The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

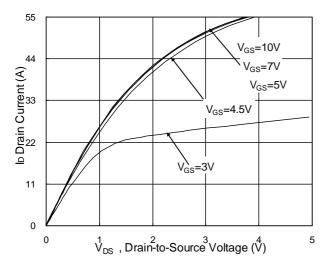


Fig.1 Typical Output Characteristics

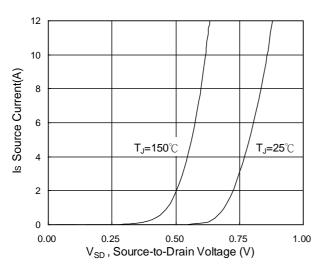


Fig.3 Forward Characteristics Of Reverse

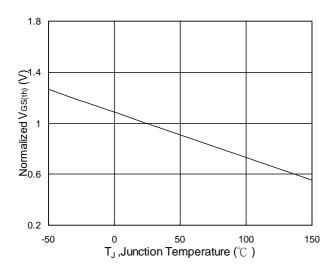


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

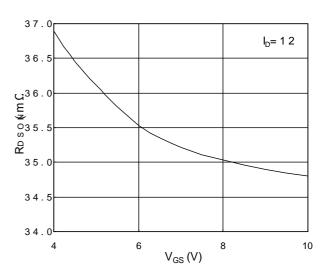


Fig.2 On-Resistance vs. Gate-Source

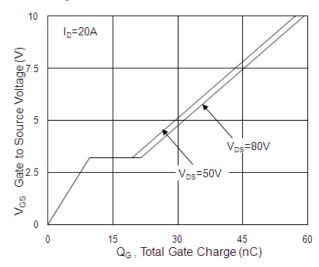


Fig.4 Gate-Charge Characteristics

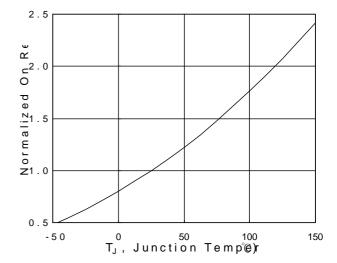
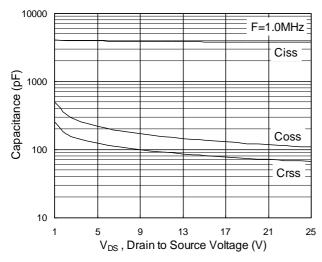


Fig.6 Normalized R_{DSON} vs. T_J



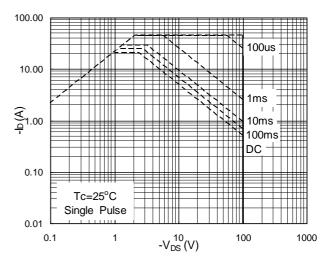


Fig.7 Capacitance

Fig.8 Safe Operating Area

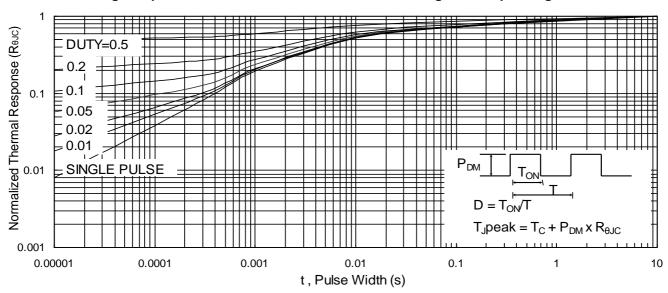


Fig.9 Normalized Maximum Transient Thermal Impedance

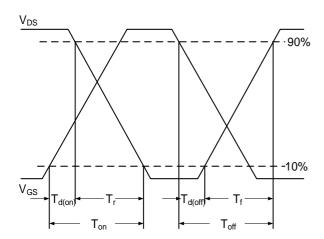


Fig.10 Switching Time Waveform

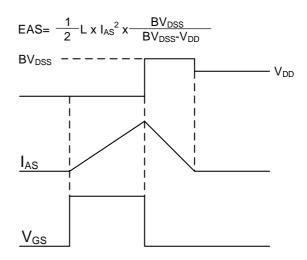
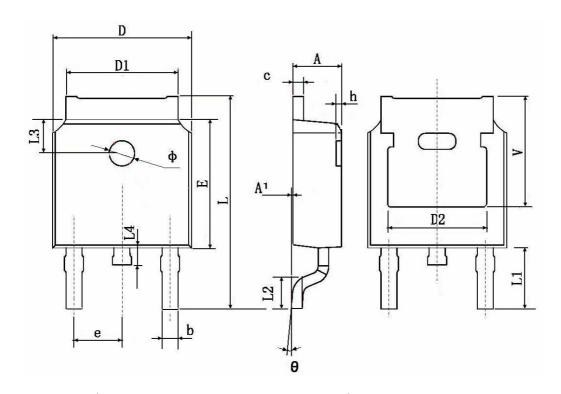


Fig.11 Unclamped Inductive Switching Waveform



TO252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		



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